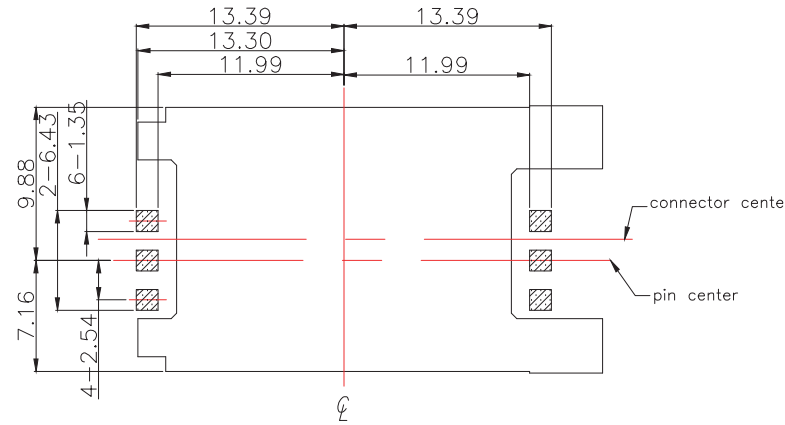
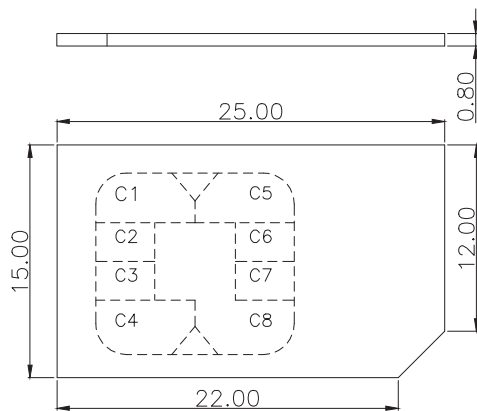


MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

- 1) MATERIAL:
HOUSING: THERMOPLASTIC,UL 94V-0, COLOR:BLACK
CONTACT: COPPER ALLOY
- 2) FINISH
CONTACT: GOLD FLASH
SOLDER AREA: TIN 100u" Min
- 3) Solder-ability
IR reflow:250°C,5sec.Max
Manual soldering:350°C ,3sec.max



PAD AREA
 KEEP OUT AREA

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

1	Contact	COPPER ALLOY	Gold FLASH	6	
2	Cover	SUS201		1	
3	Housing	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
ITEM	NAME	MATERIAL	FINISH	Q'ty	REMARK
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE:SIM CARD CONN 带铁壳 掀盖式 H2.5mm			
DECIMALS:		PAR		SIM-108-ARP6	
ANGLES:		DWN			
X.:±0.50	X':±2'	CHKD			
X.X:±0.30	X.X':±1'	APVD			
X.XX:±0.20		SCALE1:1		UNIT:MM	
CUSTOMER COPY		SIZE:A4	SHEET:1F1	REV:A	